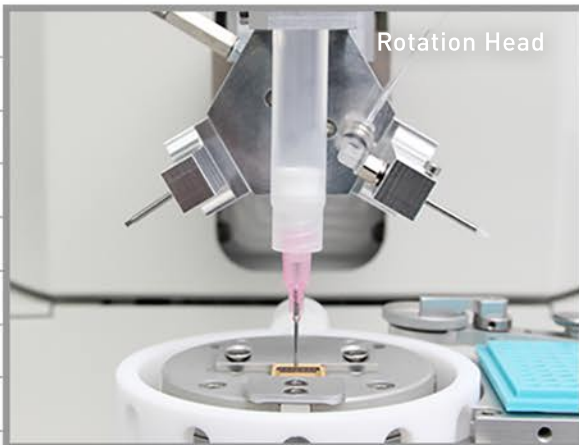




HB75 Die Bonder

Motorized Z- Axis



- + Die Placement with Precise Movements
- + Epoxy Stamping
- + Optional Epoxy Dispensing
- + Rotation Head for Quick Tool Change
- + True Vertical Movement
- + Integrated Vacuum Pump
- + Rotatable Table
- + 6,5" TFT Touch Screen
- + Bond Arm Length 165mm
- + 100 Program Storage Capacities
- + Semiautomatic and Manual Mode



+ Tool Rotation Option

HB75 Die Bonder

The HB75 is a **Bench Top Size Die Bonder**, ideal for laboratories, pilot and small scale production lines. Easy operation with **TFT Touch Screen** and direct access and simple adjustment of all parameters.

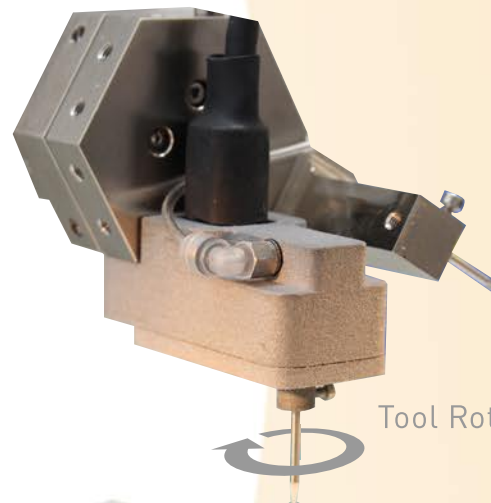
Technical Specifications

Methode	Epoxy Stamping - Die Placement
Die Size	min. 100 x 100 μm max. 10x10 mm
Bond Time	1 - 10.000 ms (1 - 20.000 sec optimal)
Bond Force	10 - 150 cN (350 cN optional)
Tool	1,58 \varnothing 19 mm
Motorized Z-Way	17 mm (0,67") 1 μm incremental steps
Bond Arm length	165 mm (6,7")
X-Y Manipulator	10 mm (0,4 ")
Parallelogram	6:1
Temperature Control	up to 250°C +/- 1°C
Power Supply	100 - 240V +/-10% 50/60 Hz 10A max.
Dimensions	680 (27") x 640 (25") x 490mm (19")
Weight	Net 42 kg
Industry Standard	CE Standard

Accessories:



H25 Dynamic Search



Tool Rotation Option



Pick & Place
H25 Heaterstage



H51 Manual Z

Specifications are subject to change without prior notice



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Made in Germany